General Specifications

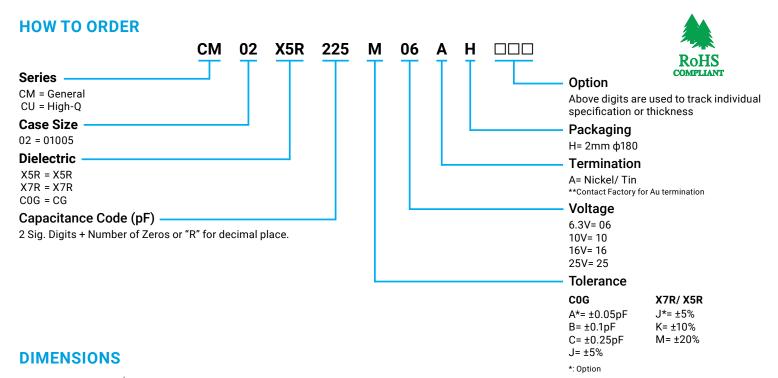


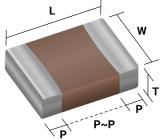


GENERAL DESCRIPTION

Offered in a complete range of products for both general and specialized applications and designed to meet a wide variety of needs. We have a worldwide network in order to supply our global customer bases quickly and efficiently. All of our products are highly reliable due to their monolithic structure of high-purity and superfine uniform ceramics and their integral internal electrodes.

Using Kyocera's latest manufacturing technology and materials with high dielectric constants, we produce extremely compact components with exceptional specifications. Our stringent quality control if every phase of production from material procurement to shipping ensures consistent manufacturing and superior quality.





PACKAGING CODE

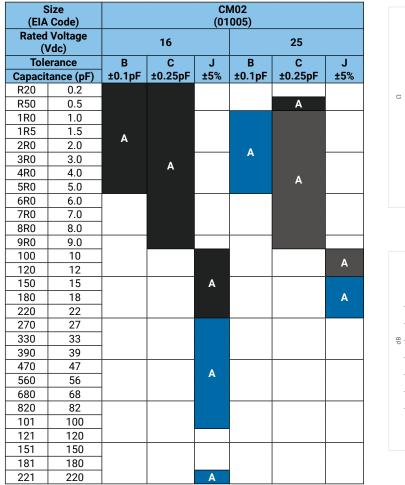
20kp	Р		8		2	
100Pcs	Taping Material		Taping Width		Pitch	
	Code	Material	Code	Width	Code	Width
	Р	Paper	8	8 mm	2	2 mm

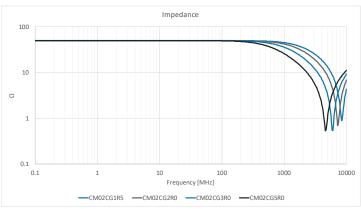
Size	Code Dimension				Dimension (mm)					
Size	EIA	JIS	Code	L	W	Т	P min.	P max.	P to P min.	ф180 Reel
02	01005	0402	A	0.4±0.02	0.2±0.02	0.2±0.02	0.07	0.14	0.13	20kp(P8/2)

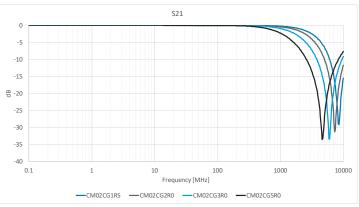


General Specifications

COG / NPO DIELECTRIC







< Standard Capacitor Value: E12 Series>

*Please Contact for capacitance values other than standard

CM Series

CU Series

2

CM & CU Series

COG / NPO CAP CHART: Alphabets denotes dimensions.

Please refer to the below table for details.

	Dimension	Dimension (mm)				Packaging				
Size	Code	Dimension (mm)		ф 180 Reel						
	ooue	L	W	Т	Code	Quantity	Taping Material	Taping Width	Cavity Pitch	
02	A	0.4±0.02	0.2±0.02	0.2±0.02	Н	20,000	Paper	8mm	2mm	



General Specifications

X5R DIELECTRIC

	Size Code)	CM02 (01005)					
	Voltage /dc)	6	.3	10	16		
Tole	erance	K	М	М	K	М	
Capa	acitace	±10%	±20%	±20%	±10%	±20%	
101	100 pF						
151	150 pF						
221	220 pF						
331	330 pF						
471	470 pF						
681	680 pF				A8	A8	
102	1000 pF				Ao	Ao	
152	1500 pF						
222	2200 pF						
472	4700 pF						
682	6800 pF						
103	10000 pF						
153	15000 pF						
223	22000 pF						
333	33000 pF	A8	A8				
473	47000 pF						
104	0.10 µF			A8			
224	0.22 µF	///#8////					
474	0.47 µF		///////////////////////////////////////				
105	1.0 µF						
225	2.2 µF						
475	4.7 μF						
106	10 µF						
156	15 µF						
226	22 µF						

< Standard Capacitor Value> Cap Value < 0.1μ F: E6 Series Cap value ≥ 0.1μ F: E3 Series

X5R Tan δ Code	Tan δ
3	5.0% max.
4	7.0% max.
5	7.5 % max.
7	10.0% max.
8	12.5% max.
9	15.0% max.
10	20.0% max.

CM Standard Spec. 1



X7R DIELECTRIC

•	Size (EIA Code)				
Rated Volt	Rated Voltage (Vdc)				
Capad	citace	16			
101	100 pF				
151	150 pF				
221	220 pF				
331	330 pF				
471	470 pF				
681	680 pF				
102	1000 pF				
152	1500 pF				
222	222 2200 pF				
< Standard C	apacitor Valu	ie>			

Cap Value < 0.1µF: E6 Series

X7R Tan δ Code	Tan δ
2	3.5% max.
3	5.0% max.
5	7.5% max.
8	12.5% max.

X7R/ X5R CAP CHART: Two digit denotes dimensions and tan δ code

Please refer to the below table for detail.

	Dimension	Dimension (mm)				Packaging				
Size	Code	Dimension (mm)		φ 180 Reel						
	Code	L	W	Т	Code	Quantity	Taping Material	Taping Width	Cavity Pitch	
02	A	0.4±0.02	0.2±0.02	0.2±0.02	Н	20,000	Paper	8mm	2mm	



The Important Information/Disclaimer is incorporated in the catalog where these specifications came from or available online at www.avx.com/disclaimer/ by reference and should be reviewed in full before placing any order.



CM/CU (Standard Spec. 1) Specifications and Test Methods

Test Items Capacitance Value (C)			Test Conditions			Specifications		
Capacitanc	ce Value (C)	Capacitance	Frequency	V	olt	Within Tolerance		
		C≤1000pF	1 MHz ±10%	0.5.		"C≥30pF : Q≥1000		
Q		C≤1000pF 1 kHz ±10% 0.5 to 5 Vrms			C<30pF : Q≥400+20C"			
		Apply the rated voltage f	or 1 minute, and mea	sure it in norma	al	•		
Insulation Re	esistance (IR)	temperature and humidity. The charge and discharge current of the				Over 10000MΩ or 500MΩnµF, whichever is less		
		capacitor must not excee	ed 50mA.					
		Apply *3 times the rated	voltage for 1 to 5 sec	onds twice. Th	e charge and			
Dielectric Resistance		discharge current of the		xceed 50mA.		No defect		
		*CU02CAR20-120/25V:1	twice					
	arance	Microscope				No defect		
Termination Strength		Apply a sideward force o				No defect		
Bending	Strength	Glass epoxy PCB: Fulcru		ration time 10	Seconds.	No Significant damage with 1mm bending.		
	Appearance	"Vibration Frequency: 10-	-55 (Hz)			No defect		
Vibration	ΔC	Amplitude: 1.5mm				Within Tolerance		
Test	Q	Sweeping Condition: 10		e in X, Y and Z		"C≥30pF : Q≥1000		
	ч 	Directions: 2 hours each,	6 hours total"			C<30pF : Q≥400+20C"		
	Appearance	"Soak the Sample in 260"	°C ± 5°C solder for 10)±0.5 seconds a	and place in	No defect		
	ΔC	normal temperature and				Within 1.2 E% or 1.0.25 pF whichover is larger		
		(Pre-heating conditions)	,		Within \pm 2.5% or \pm 0.25 pF, whichever is larger			
Soldering	Q	Order	Temperature	Time		"C≥30pF : Q≥1000		
Heat	ų	1	80-100°C	2 min		C<30pF : Q≥400+20C"		
Resistant	IR	2	150-200°C	2 min		Over 10000MΩ or 500MΩnµF, whichever is less		
		The charge and discharg		oitor must not	avood			
	Withstanding	50mA for IR and Withsta			exceeu	Resist without problem		
	Voltage			incinicint.				
			Soak Condition:		_			
Solde	rability	Sn-3AG-0.		3 ±0.5 sec.		Solder Coverage : 95% min.		
		Sn63 Sol	der 235 ±5°C	2 ±0.5 sec.				
	Appearance	(Cycle)				No defect		
	ΔC	Room Temperature (3mi	n.)			Within ± 2.5% or ± 0.25 pF, whichever is larger		
		Lowest Operating Tempe			"C≥30pF : Q≥1000			
Temperature	Q	Room Temperature (3 m	in.)`	C<30pF : Q≥400+20C"				
Cycle	IR	Highest Operating Temp		Over 10000MΩ or 500MΩnµF, whichever is less				
	Withstanding	After 5 cycles, measure a						
	Voltage	The charge and discharg			exceed	Resist without problem		
		50mA for IR and Withsta	nding Voltage measu	irement."				
	Appearance	After applying the rated v	oltage for 500-512 h	ours in the con	dition	No defect		
Moisture	ΔC	of 40°C± 2°C and 90 to 9				Within ± 7.5% or ± 0.75 pF, whichever is larger		
Resistant	Q	temperature and humidit				"C≥30pF : Q≥200		
Load		The charge and discharg	e current of the capa	citor must not	exceed	C<30pF : Q≥100+10C/3"		
	IR	50mA for IR measureme	nt.			Over 500M Ω or 25M Ω nµF, whichever is less.		
	Appearance					No defect		
		After applying *twice the	rated voltage in the	condition of 12	5+3°C for	Within ± 3% or ± 0.3 pF,		
	ΔC	After applying *twice the rated voltage in the condition of $125\pm3^{\circ}$ C for 1000-1012 hours, measure the sample after 24 ± 2 hours in normal temperature and humidity. The charge and discharge current of the						
High-						whichever is larger		
Temperature		capacitor must not excee				C≥30pF : Q≥350		
Load	Q					10pF <c<30pf 2<="" :="" q≥275+5c="" td=""></c<30pf>		
		** Applied voltages for respective products are indicated in the chart below.				C<10pF : Q≥200+10C		
	IR			Over 1000MΩ or 50MΩnµF,				
		1				whichever is less.		

Please Ask for individual specification for the hatched range in previous chart.

Voltage to be applied in the High Temperature Load (Applied Voltage is the multiple of the rated voltage)

Applied Voltage	Rated Voltage	Products
X 1.0	16V	CM02CΔ221
★1.2	24V	CM02CAR20-120





CM Series (Standard Spec. 1 & 2) Specifications and Test Methods

Test Items		Test Conditions	Specifications Standard Spec. 1	Specifications Standard Spec. 2
Capacitand	e Value (C)	Measure after heat treatment	Within Tolerance	Within Tolerance
Tan δ		$\begin{tabular}{ c c c c c c c c c c c c c c c c c c c$	capacitance chart	Refer to capacitance chart
Insulation Re	esistance (IR)	Apply the rated voltage for 1 minute, and measure it in normal tempera and humidity. The charge and discharge current of the capacitor must not exceed 50mA.		Over 50MΩ - µf
Dielectric	Resistance	Apply 2.5 times the rated voltage for 1-5 seconds. The charge and discharge current of the capacitor must not exceed 50mA.	No defect	No defect
Арреа	arance	Microscope	No defect	No defect
Terminatio	on Strength	Apply a sidewards force of 100g (1N) to PCB-mounted sample.	No defect	No defect
Bending	Strength	Glass epoxy PCB: Fulcrum spacing: 90mm, duration time 10 seconds.	No Significant damage with 1mm bending.	No Significant damage with 1mm bending.
	Appearance	Take the initial value after heat treatment. Vibration Frequency: 10-55 (Hz)	No defect	No defect
Vibration Test	ΔC	Amplitude: 1.5mm Sweeping Condition: 10_55_10 Hz/ 1 minute in X, Y and Z Directions: 2 hours each, 6 hours total, and place in normal temperature	Within Tolerance	Within Tolerance
	Tan δ	and humidity. Measure the sample after heat treatment.	Within Tolerance	Within Tolerance
	Appearance	Take the initial value after heat treatment.	No defect	No defect
	ΔC	Soak the Sample in $260^{\circ}C \pm 5^{\circ}C$ solder for 10 ± 0.5 seconds and place in	Within ± 7.5%	Within ± 7.5%
	Tan δ	normal temperature and humidity. Measure after heat treatment.	Within Tolerance	Within Tolerance
Soldering Heat	IR	(Pre-heating conditions)	Over 10000MΩ or 500MΩ-µF, whichever is less.	Over 50MΩ - µF
Resistant	Withstanding Voltage	Order Temperature Time 1 80-100°C 2 min 2 150-200°C 2 min The charge and discharge current of the capacitor must not exceed 50 for IR and Withstanding Voltage measurement.	nA Resist without problem	Resist without problem
Solde	rability	Soak Condition: Sn-3AG-0.5Cu 245±5°C 3±0.5 sec. Sn63 Solder 235±5°C 3±0.5 sec.	Solder Coverage : 90% min.	Solder Coverage : 90% min.
	Appearance	Take initial value after heat treatment.	No defect	No defect
	ΔC	(Cycle)	Within ± 7.5%	Within ± 7.5%
	Tan δ	Room Temperature (3min.)_ Lowest Operating Temperature (30 min.)	Within Tolerance	Within Tolerance
emperature Cycle	IR	Room Temperature (3 min.) Highest Operating Temperature (30 min.)	Over 10000MΩ or 500MΩ-µF, whichever is less.	Over 50MΩ - µF
	Withstanding Voltage	After 5 cycles, measure after heat treatment. The charge and discharge current of the capacitor must not exceed 50 for IR and Withstanding Voltage measurement.	nA Resist without problem	Resist without problem
	Appearance	Take the initial value after heat treatment. After applying the rated volta	ge No defect	No defect
Moisture	ΔC	for 500-512 hours in the condition of 40°C± 2°C and 90 to 95% RH, plac	Within ± 12.5%	Within ± 12.5%
Resistant	Tan δ	in normal temperature and humidity, then measure the sample after he		200% max. of initial value
Load	IR	treatment. The charge and discharge current of the capacitor must not exceed 50mA for IR measurement.	Over 500MΩ or 25MΩ=µF, whichever is less.	Over 10MΩ - µF
	Appearance	Take the initial value after heat treatment. After applying *twice the rate voltage in the highest operating temperature for 1000-1012 hours, mea		No defect
High-	ΔC	the sample after heat treatment in normal temperature and humidity. T	Within ± 12.5%	Within ± 12.5%
Temperature	Tan δ	charge and discharge current of the capacitor must not exceed 50mA f IR measurement.	200% max. of initial value	200% max. of initial value
Load	IR	X5R Spec 2:Apply 1.0 times when the rated voltage is 4V or less. X7R/X7R Spec 1: Apply 1.5 times when the rated Voltage is 10V or less Applied Voltages for respective products are indicated in the chart below		Over 10MΩ - µF
Linet Tr	eatment	Expose sample to temperature of 140-150°C for 1 hour and leave the s	ample in normal temperature and humidi	ity for 24 ± 2 hours.

Voltage to be applied in the High Temperature Load (Applied Voltage is the multiple of the rated voltage)

Applied Voltage	Rated Voltage	Products
X 1.0	10V	CM02X5R104
X 1.3	6.3V	CM02X5R153-104
X 1.5	16V	CM02X5R101-103, CM02X7R222

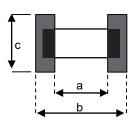
Applied Voltage	Rated Voltage	Products
X 1.0	6.3V	CM02X5R224,CM02X5R474





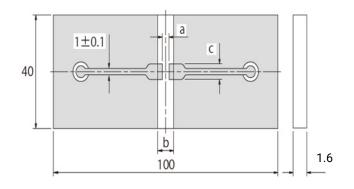
Test Conditions and Standards

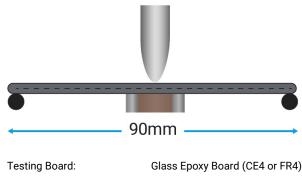
Substrate for Adhesion Strength Test, Vibration Test, Soldering Heat Resistance Test, Temperature Cycle Test, Load Humidity Test, High-Temperature with Loading Test.



			Unit: mm
Size (EIA Code)	Α	В	С
02 (01005)	0.15	0.5	0.20

SUBSTRATE FOR BENDING TEST

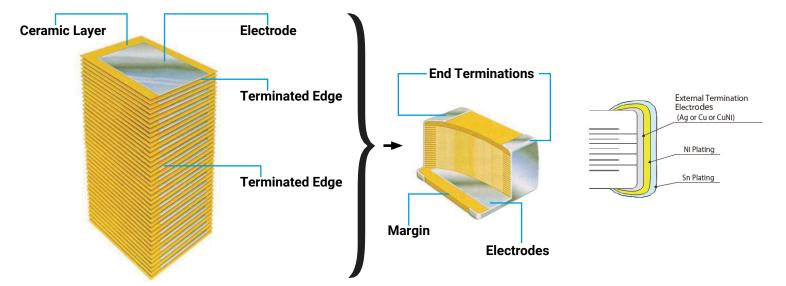




Testing Board Thickness: Circuit Thickness:

Glass Epoxy Board (CE4 or FR4) 1.6 ± 0.2mm* 0.04 ± 0.01mm

STRUCTURE

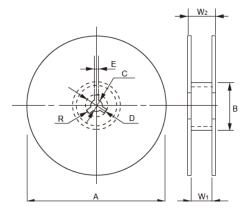


- Please contact your local AVX Sales office or distributor for specifications not covered in this catalog.
- Capacitance range is subject to change without notice
- Please contact sales representative to confirm compatibility with your application.



Packaging Options

TAPE & REEL QUANTITIES



Code Reel	А	В	С	D	
7- inch Reel (Code: H)	180 ⁺⁰ -2.0	φ 60 min.	13 ±0.5	21 ±0.8	
Code Reel	E	W ₁	W ₂	R	
7- inch Reel (Code: H)	2.0 ±0.5	10.5 ±1.5	16.5 max.	1.0	

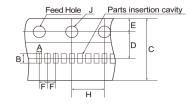
CARRIER TAPE

Size

(EIA Code)

02 (01005)*

F = 1mm



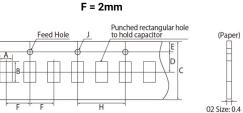
Α

0.25 ± 0.03



 3.5 ± 0.05

(Paper)



	Size: 0.4 max. Size: 0.5 max.		F -	н	02 Size: 0.4 max.		
•	D	F	-	6		Carrie	r Tape
U	U	<u>د</u>	-	6	J	Width	Material

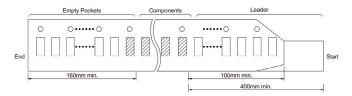
 4.0 ± 0.1

1.5 + 0.1

8mm

Paper

DETAIL OF LEADER AND TRAILER



В

 0.45 ± 0.03

ADHESIVE TAPE

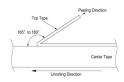
1. The exfoliative strength when peeling off the top tape from the carrier tape by the method of the following figure shall be *0.1 to 0.5N.

1.75 ± 0.1

 2.0 ± 0.05

- 2. When the top tape is peeled off, the adhesive stays on the top tape.
- 3. Chip capacitors will be in a state free without being stuck on the thermal adhesive tape.2

8.0 ± 0.3



CARRIER TAPE

- 1. Chip will not fall off from carrier tape or carrier tape will not be damaged by bending than within a radius of 25mm.
- 2. The chip are inserted continuously without any empty pocket.
- 3. Chip will not be mis-mounted because of too big clearance between components and cavity. Also the waste of carrier tape will not fill a nozzle hole of mounting machine.







0.20 to 0.23

Recommended Land Dimensions

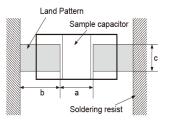
0.12 to 0.18

Surface Mounting Information

DIMENSIONS FOR RECOMMENDED TYPICAL LAND

Since the amount of solder (size of fillet) to be used has direct influence on the capacitor after mounting, the sufficient consideration is necessary. When the amounts of solder is too much, the stress that a capacitor receives becomes larger. It may become the cause of a crack in the capacitor. When the land design of printed wiring board is considered, it is necessary to set up the form and size of land pattern so that the amount of solder is suitable.

(General)



MOUNTING DESIGN

The chip could crack if the PCB warps during processing after the chip has been soldered.

RECOMMENDED CHIP POSITION ON PCB TO MINIMIZE STRESS FROM PCB WARPAGE

GENERAL

'Size

(EIA Code)'

02

(01005)

Dimension

0.4± 0.02

w

0.2±0.02

* Recommended land dimensions may differ depending on dimensional tolerance

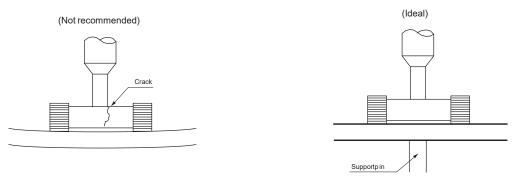
а

0.13 to 0.20



MOUNTING

- 1. If the position of the vacuum nozzle is too low, a large force may be applied to the chip capacitor during mounting, resulting in cracking.
- 2. During mounting, set the nozzle pressure to a static load of 1 to 3 N.
- 3. To minimize the shock of the vacuum nozzle, provide a support pin on the back of the PCB to minimize PCB flexure.



4. Bottom position of pick up nozzle should be adjusted to the top surface of a substrate when camber is corrected.

RESIN MOLD

- 1. If a large amount of resin is used for molding the chip, cracks may occur due to contraction stress during curing. To avoid such cracks, use a low shrinkage resin.
- 2. The insulation resistance of the chip will degrade due to moisture absorption. Use a low moisture absorption resin.
- 3. Check carefully that the resin does not generate a decomposition gas or reaction gas during the curing process or during normal storage. Such gases may crack the chip capacitor or damage the device itself.



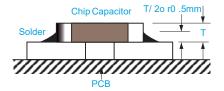


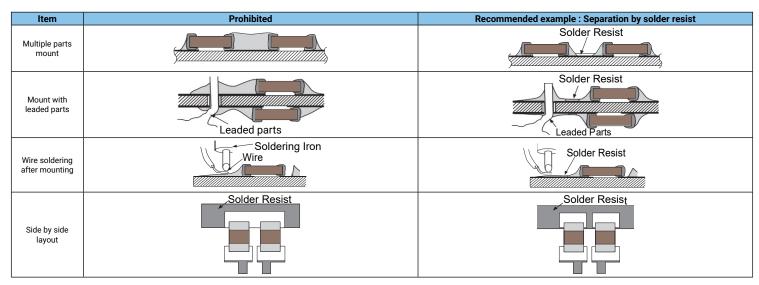
Surface Mounting Information

SOLDERING METHOD

The recommended fillet height shall be 1/2 of the thickness of capacitors or 0.5mm. When mounting two or more capacitors in the common land, it is necessary to separate the land with the solder resist strike so that it may become the exclusive land of each capacitor.

IDEAL SOLDER HEIGHT



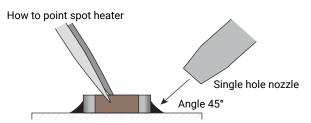


DESIGN OF PRINTED CIRCUIT AND SOLDERING

- 1. Ceramic is easily damaged by rapid heating or cooling. If some heat shock is unavoidable, preheat enough to limit the temperature difference (Delta T) to within 150 degree Celsius.
- 2. The product size 1.6×0.8mm to 3.2×1.6mm can be used in reflow and wave soldering, and the product size of bigger than 3.2×1.6mm, or smaller than 1.6 ×0.8mm can be used in reflow. Circuit shortage and smoking can be created by using capacitors which are used neglecting the above caution.
- 3. Please see our recommended soldering conditions.
- 4. In case of using Sn-Zn Solder, please contact us in advance.
- 5. The following condition is recommended for spot heater application.

RECOMMENDED SPOT HEATER CONDITION

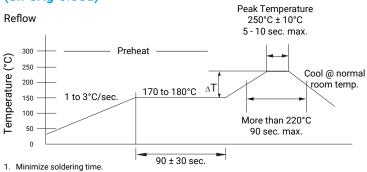
Item	Condition
Distance	5mm min.
Angle	45°
Projection Temp.	400℃ max.
Flow Rate	Set at the minimum
Nozzle Diameter	2φ to 4φ (Single hole type)
Application time	10 sec max.



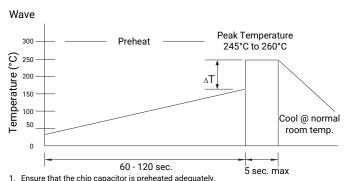


Surface Mounting Information

RECOMMENDED TEMPERATURE PROFILE (Sn-3Ag-0.5Cu)

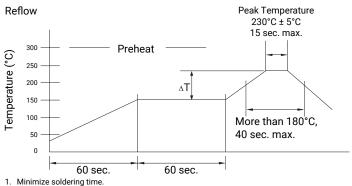


- Ensure that allowable temperature difference does not exceed 150°C. 2.
- 3. Ensure that allowable temperature difference does not exceed 130°C for 3.2×2.5mm size or larger.
- 4. MLCC can withstand the above reflow conditions up to 3times. 5. N2atmosphere is recommended for reflow of products of 0.4mm×0.2mm size or smaller.



- 2. Ensure that the temperature difference (ΔT) does not exceed 150°C.
- З. Cool naturally after soldering.MLCC can withstand the above reflow conditions up to 3 times.
- 4 Wave soldering is not applicable for chips with size of 3.2×2.5mm or larger of 1.0×0.5mm or smaller and capacitor arrays

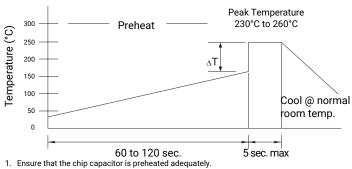
RECOMMENDED TEMPERATURE PROFILE (63n Solder)



2. Ensure that the temperature difference (ΔT) does not exceed 150°C.

- Ensure that the temperature difference (Δ T) does not exceed 130°C for 3.2×2.5mm size or larger. MLCC can withstand the above reflow conditions up to 3 times. 3. 4.

Wave



Ensure that the temperature difference (ΔT) does not exceed 150°C.
 Cool naturally after soldering.

4. Wave soldering is not applicable for chips with size of 3.2×2.5mm or larger of 1.0×0.5mm or smaller and capacitor arrays





CIRCUIT DESIGN

- 1. Once application and assembly environments have been checked, the capacitor may be used in conformance with the rating and performance which are provided in both the catalog and the specifications. Use exceeding that which is specified may result in inferior performance or cause a short, open, smoking, or flaming to occur, etc.
- 2. Please consult the manufacturer in advance when the capacitor is used in devices such as: devices which deal with human life, i.e. medical devices; which are highly public orientated; and devices which demand a high standard of liability. Accident or malfunction of devices such as medical devices, space equipment and devices having to do with atomic power could generate grave consequence with respect to human lives or, possibly, a portion of the public. Capacitors used in these devices may require high reliability design different from that of general-purpose capacitors.
- 3. Please use the capacitors in conformance with the operating temperature provided in both the catalog and the specifications. Be especially cautious not to exceed the maximum temperature. In the situation the maximum temperature set forth in both the catalog and specifications is exceeded, the capacitor's insulation resistance may deteriorate, power may suddenly surge and short-circuit may occur. The capacitor has a loss and may selfheat due to equivalent series resistance when alternating electric current is passed there through. As this effect becomes especially pronounced in high frequency circuits, please exercise caution. When using the capacitor remains under the maximum temperature for usage. Also, please make certain temperature rises remain below 20°C.
- 4. Please keep voltage under the rated voltage which is applied to the capacitor. Also, please make certain the peak voltage remains below the rated voltage when AC voltage is super-imposed to the DC voltage. In the situation where AC or pulse voltage is employed, ensure average peak voltage does not exceed the rated voltage. Exceeding the rated voltage provided in both catalog and specifications may lead to defective withstanding voltage or, in worst case situations, may cause the capacitor to smoke or flame.
- 5. When the capacitor is to be employed in a circuit in which there is continuous application of a high frequency voltage or a steep pulse voltage, even though it is within the rated voltage, please inquire to the manufacturer. In the situation the capacitor is to be employed using a high frequency AC voltage or an extremely fast rising pulse voltage, even though it is within the rated voltage, it is possible capacitor reliability will deteriorate.
- 6. It is a common phenomenon of high-dielectric products to have a deteriorated amount of static electricity due to the application of DC voltage. Due caution is necessary as the degree of deterioration varies depending on the quality of capacitor materials, capacity, as well as the load voltage at the time of operation.
- 7. Do not use the capacitor in an environment where it might easily exceed the respective provisions concerning shock and vibration specified in the catalog and specifications. In addition, it is a common piezo phenomenon of high dielectric products to have some voltage due to vibration or to have noise due to voltage change. Please contact sales in such case.
- 8. If the electrostatic capacity value of the delivered capacitor is within the specified tolerance, please consider this when designing the respective product in order that the assembled product function appropriately.
- 9. Please contact us upon using conductive adhesives.

STORAGE

- 1. If the component is stored in minimal packaging (a heat-sealed or zippered plastic bag), the bag should be kept closed. Once the bag has been opened, reseal it or store it in a desiccator.
- 2. Keep storage place temperature +5 to +40 °C, humidity 20 to 70% RH. See JIS C 6 0721-3-1, class 1K2 for other climatic conditions.
- 3. The storage atmosphere must be free of corrosive gas such as sulfur dioxide and chlorine. Also, avoid exposing the product to saline moisture. If the product is exposed to such atmospheres, the terminals will oxidize and solderability will be effected.
- 4. Precautions 1) to 3) apply to chip capacitors packaged in carrier tapes.
- 5. The solderability is assured for 6 months from our shipping date if the above storage precautions are followed.



Part Number List



General CM02 SeriesSize (JIS Code): 01005(0402)# Packaging Code (Packaging quantity): H(20,000pcs.)

Dielectric code C∆	Capacitance	□:Tolerance	Voltage [V]	Part Number		Dimension			# Packaging Code
					Q	L [mm]	W [mm]	T [mm]	(quantity)
	1.0pF			CM02C ∆ 1R0 🗆 25A#	420	0.4± 0.02	0.2± 0.02	0.2± 0.02	Н
	1.5pF			CM02C ∆ 1R5 🗆 25A#	430	0.4± 0.02	0.2± 0.02	0.2± 0.02	Н
	2.0pF	B: ± 0.1pF C: ± 0.25pF	25	CM02C ∆ 2R0 🗆 25A#	440	0.4± 0.02	0.2± 0.02	0.2± 0.02	Н
	3.0pF		25	CM02C ∆ 3R0 🗆 25A#	460	0.4± 0.02	0.2± 0.02	0.2± 0.02	Н
	4.0pF			CM02C ∆ 4R0 🗆 25A#	480	0.4± 0.02	0.2± 0.02	0.2± 0.02	Н
	5.0pF			CM02C ∆ 5R0 🗆 25A#	500	0.4± 0.02	0.2± 0.02	0.2± 0.02	Н
	6.0pF			CM02C ∆ 6R0 🗆 25A#	520	0.4± 0.02	0.2± 0.02	0.2± 0.02	Н
	7.0pF	0 . 0 05 5	05	CM02C ∆ 7R0 □ 25A#	540	0.4± 0.02	0.2± 0.02	0.2± 0.02	Н
	8.0pF	C: ± 0.25pF	25	CM02C ∆ 8R0 □ 25A#	560	0.4± 0.02	0.2± 0.02	0.2±0.02	Н
	9.0pF			CM02C ∆ 9R0 □ 25A#	580	0.4± 0.02	0.2± 0.02	0.2±0.02	Н
	10pF			CM02C ∆ 100 □ 25A#	600	0.4± 0.02	0.2± 0.02	0.2±0.02	Н
	12pF			CM02C ∆ 120 □ 25A#	640	0.4± 0.02	0.2± 0.02	0.2±0.02	Н
CG	15pF	J: ± 5%	25	CM02C ∆ 150 □ 25A#	700	0.4± 0.02	0.2± 0.02	0.2± 0.02	Н
	18pF		-	CM02C ∆ 180 □ 25A#	760	0.4± 0.02	0.2± 0.02	0.2± 0.02	Н
	22pF			CM02C ∆ 220 □ 25A#	840	0.4± 0.02	0.2± 0.02	0.2±0.02	Н
	27pF		16	CM02C ∆ 270 □ 16A#	940	0.4± 0.02	0.2± 0.02	0.2± 0.02	Н
	33pF			CM02C ∆ 330 □ 16A#	1000	0.4± 0.02	0.2± 0.02	0.2±0.02	н
	39pF			CM02C ∆ 390 □ 16A#	1000	0.4± 0.02	0.2± 0.02	0.2± 0.02	н
	47pF			CM02C ∆ 470 □ 16A#	1000	0.4± 0.02	0.2± 0.02	0.2± 0.02	Н
	56pF	J: ± 5%		CM02C ∆ 560 □ 16A#	1000	0.4± 0.02	0.2± 0.02	0.2± 0.02	н
	68pF	J. ± 5%		CM02C ∆ 680 □ 16A#	1000	0.4± 0.02	0.2± 0.02	0.2±0.02	н
	82pF			CM02C ∆ 820 □ 16A#	1000	0.4± 0.02	0.2± 0.02	0.2±0.02	н
	100pF			CM02C ∆ 820 ⊟ 16A#	1000	0.4± 0.02	0.2± 0.02	0.2±0.02	н
	220pF			CM02C Δ 101 □ 16A# CM02C Δ 221 □ 16A#	1000	0.4± 0.02	0.2± 0.02	0.2±0.02	<u>н</u>
	100pF			CM02C Z 221 🗆 16A#	12.5	0.4±0.02 0.4±0.02	0.2±0.02	0.2 ± 0.02	<u>н</u> Н
	150pF			CM02X5R101 🗆 16A#	12.5	0.4 ± 0.02 0.4 ± 0.02	0.2 ± 0.02	0.2 ± 0.02	<u>н</u> Н
		-							
	220pF			CM02X5R221 □ 16A#	12.5	0.4 ± 0.02	0.2 ± 0.02	0.2 ± 0.02	H
	330pF			CM02X5R331 □ 16A#	12.5	0.4 ± 0.02	0.2 ± 0.02	0.2 ± 0.02	н
	470pF			CM02X5R471 16A#	12.5	0.4 ± 0.02	0.2 ± 0.02	0.2 ± 0.02	H
	680pF	K: ± 10%	16	CM02X5R681 16A#	12.5	0.4 ± 0.02	0.2 ± 0.02	0.2 ± 0.02	Н
	1000pF	M: ± 20%		CM02X5R102 16A#	12.5	0.4 ± 0.02	0.2 ± 0.02	0.2 ± 0.02	Н
	1500pF			CM02X5R152 16A#	12.5	0.4 ± 0.02	0.2 ± 0.02	0.2 ± 0.02	Н
	2200pF			CM02X5R222 16A#	12.5	0.4 ± 0.02	0.2 ± 0.02	0.2 ± 0.02	Н
	4700pF			CM02X5R472 16A#	12.5	0.4 ± 0.02	0.2 ± 0.02	0.2 ± 0.02	Н
X5R	6800pF			CM02X5R682 16A#	12.5	0.4 ± 0.02	0.2 ± 0.02	0.2 ± 0.02	Н
	10000pF			CM02X5R103 🗆 16A#	12.5	0.4 ± 0.02	0.2 ± 0.02	0.2 ± 0.02	Н
	15000pF			CM02X5R153 🗆 06A#	12.5	0.4 ± 0.02	0.2 ± 0.02	0.2 ± 0.02	Н
	22000pF	K: ± 10%	6.3	CM02X5R223 🗆 06A#	12.5	0.4 ± 0.02	0.2 ± 0.02	0.2 ± 0.02	Н
	33000pF	M: ± 20%	-10	CM02X5R333 🗆 06A#	12.5	0.4 ± 0.02	0.2 ± 0.02	0.2 ± 0.02	Н
	47000pF			CM02X5R473 🗆 06A#	12.5	0.4 ± 0.02	0.2 ± 0.02	0.2 ± 0.02	Н
	0.10µF	M: ± 20%	10	CM02X5R104 🗆 10A#	12.5	0.4 ± 0.02	0.2 ± 0.02	0.2 ± 0.02	Н
	0.10µF	K: ± 10% M: ± 20%	6.3	CM02X5R104 🗆 06A#	12.5	0.4 ± 0.02	0.2 ± 0.02	0.2 ± 0.02	Н
	0.22µF	i	6.0	CM02X5R224M06A#	12.5	0.4 ± 0.02	0.2 ± 0.02	0.2 ± 0.02	Н
	0.47µF	M: ± 20%	6.3	CM02X5R474M06A#	12.5	0.4 ± 0.02	0.2 ± 0.02	0.2 ± 0.02	Н
X7R	2200µF	K: ± 10% M: ± 20%	16	CM02X7R222 🗆 16A#	12.5	0.4 ± 0.02	0.2 ± 0.02	0.2 ± 0.02	н



Part Number List



General CM02 SeriesSize (JIS Code): 01005(0402)# Packaging Code (Packaging quantity): H(20,000pcs.)

Dielectric code C∆			Voltage	Part Number		Dimension	# Packaging Code	
	Capacitance □:1	□:Tolerance	[V]		L [mm]	W [mm]	T [mm]	(quantity)
	R50			CU02C ∆ R50 □ 25AH	0.4± 0.02	0.2±0.02	0.2± 0.02	Н
	1.0pF			CU02C ∆ 1R0 🗆 25AH	0.4± 0.02	0.2±0.02	0.2± 0.02	Н
	1.5pF			CU02C ∆ 1R5 🗆 25AH	0.4± 0.02	0.2±0.02	0.2± 0.02	Н
	2.0pF			CU02C ∆ 2R0 🗆 25AH	0.4± 0.02	0.2± 0.02	0.2± 0.02	Н
	3.0pF			CU02C ∆ 3R0 🗆 25AH	0.4± 0.02	0.2± 0.02	0.2± 0.02	Н
	4.0pF	C: ± 0.25pF	25	CU02C ∆ 4R0 □ 25AH	0.4± 0.02	0.2±0.02	0.2± 0.02	Н
	5.0pF			CU02C ∆ 5R0 □ 25AH	0.4± 0.02	0.2±0.02	0.2± 0.02	Н
	6.0pF			CU02C ∆ 6R0 □ 25AH	0.4± 0.02	0.2±0.02	0.2± 0.02	Н
	7.0pF			CU02C ∆ 7R0 🗆 25AH	0.4± 0.02	0.2±0.02	0.2± 0.02	Н
	8.0pF			CU02C ∆ 8R0 □ 25AH	0.4± 0.02	0.2±0.02	0.2± 0.02	Н
	9.0pF			CU02C ∆ 9R0 □ 25AH	0.4± 0.02	0.2± 0.02	0.2± 0.02	Н
~~	10pF	J: ± 5%	25	CU02C ∆ 100 □ 25AH	0.4± 0.02	0.2± 0.02	0.2± 0.02	Н
CG	12pF			CU02C ∆ 120 □ 25AH	0.4± 0.02	0.2±0.02	0.2± 0.02	Н
	R20	"B: ± 0.1pF C: ± 0.25pF "		CU02C ∆ R20 □ 16AH	0.4± 0.02	0.2± 0.02	0.2± 0.02	Н
	R50			CU02C ∆ R50 □ 16AH	0.4± 0.02	0.2±0.02	0.2± 0.02	Н
	1R0			CU02C ∆ 1R0 □ 16AH	0.4± 0.02	0.2±0.02	0.2± 0.02	Н
	1R5			CU02C ∆ 1R5 🗆 16AH	0.4± 0.02	0.2±0.02	0.2± 0.02	Н
	2R0		16	CU02C ∆ 2R0 □ 16AH	0.4± 0.02	0.2±0.02	0.2± 0.02	Н
	3R0			CU02C ∆ 3R0 □ 16AH	0.4± 0.02	0.2± 0.02	0.2± 0.02	Н
	4R0			CU02C ∆ 4R0 □ 16AH	0.4± 0.02	0.2±0.02	0.2± 0.02	Н
-	5R0			CU02C ∆ 5R0 □ 16AH	0.4± 0.02	0.2±0.02	0.2± 0.02	Н
	6R0		16	CU02C ∆ 6R0 □ 16AH	0.4± 0.02	0.2±0.02	0.2± 0.02	Н
	7R0			CU02C ∆ 7R0 □ 16AH	0.4± 0.02	0.2±0.02	0.2± 0.02	Н
	8R0	C: ± 0.25pF		CU02C ∆ 8R0 □ 16AH	0.4± 0.02	0.2± 0.02	0.2± 0.02	Н
	9R0			CU02C ∆ 9R0 □ 16AH	0.4± 0.02	0.2±0.02	0.2± 0.02	Н
	10pF			CU02C ∆ 100 □ 16AH	0.4± 0.02	0.2± 0.02	0.2± 0.02	Н
VED	12pF	J: ± 5%	16	CU02C ∆ 120 □ 16AH	0.4± 0.02	0.2± 0.02	0.2± 0.02	Н
X5R	15pF			CU02C ∆ 150 □ 16AH	0.4± 0.02	0.2± 0.02	0.2± 0.02	Н
	18pF			CU02C ∆ 180 🗆 16AH	0.4± 0.02	0.2± 0.02	0.2± 0.02	Н
-	22pF	1		CU02C ∆ 220 □ 16AH	0.4± 0.02	0.2±0.02	0.2± 0.02	Н



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CM02X5R474M06AH CM02CG1R5B25AH CM02CG220J25AH CM02CG221J16AH CM02CG5R0C25AH CM02CG6R0C25AH CM02CG7R0C25AH CU02CG5R0B16AH CU02CG1R0B16AH CU02CG2R0C25AH CM02CG330J16AH CM02X5R104M06AH CU02CG120J25AH CU02CG3R0C16AH CM02CG150J25AH CM02X5R223M06AH CM02X5R224M06AH CM02X5R682M16AH CU02CG150J16AH CU02CG2R0B16AH CM02CG100J25AH CM02X5R102K16AH CM02X5R103M16AH CU02CG120J16AH CU02CG3R0B16AH CU02CG3R0C25AH CU02CG4R0B16AH CU02CGR50B16AH CM02X5R103K16AH CM02X5R222M16AH CM02X5R223K06AH CM02X5R224K06AH CM02X7R222K16AH CM02X7R222M16AH CM02CG101J16AH CM02CG390J16AH CM02CG470J16AH CM02X5R333K06AH CM02X5R681M16AH CM02CG560J16AH CM02CG8R0C25AH CM02X5R101K16AH CM02X5R153M06AH CM02X5R221M16AH CM02X5R331K16AH CU02CGR20B16AH CU02CGR20C16AH CU02CGR50C16AH CM02CG1R0B25AH CM02CG2R0B25AH CM02CG4R0B25AH CU02CG100J16AH CU02CG100J25AH CU02CG4R0C16AH CU02CG180J16AH CU02CG5R0C16AH CM02CG3R0B25AH CM02CG3R0C25AH CM02X5R102M16AH CM02X5R682K16AH CM02CG2R0C25AH CM02X5R101M16AH CM02X5R104M10AH CM02X5R221K16AH CM02X5R331M16AH CU02CG2R0C16AH CU02CG8R0C25AH CU02CG9R0C25AH CU02CGR50C25AH CM02CG180J25AH CM02CG270J16AH CU02CG1R0C16AH CU02CG220J16AH CU02CG4R0C25AH CU02CG5R0C25AH CU02CG8R0C16AH CU02CG9R0C16AH CM02X5R473K06AH CM02X5R681K16AH CM02X5R151K16AH CM02X5R473M06AH CM02CG5R0B25AH CM02CG1R0C25AH CM02CG9R0C25AH CM02X5R104K06AH CM02X5R222K16AH CM02X5R333M06AH CU02CG1R0C25AH CU02CG1R5C16AH CU02CG6R0C16AH CU02CG7R0C25AH CM02CG120J25AH CM02CG4R0C25AH CU02CG1R5C25AH CM02X5R153K06AH CM02X5R471K16AH CM02X5R472K16AH CM02CG1R5C25AH CM02CG680J16AH CM02CG820J16AH